ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pan	PC. Bannockl	ourn. Illinois. A	ll rights reserved utions.	under both	This docume level parts, t	ent is a declaration en declaration en	on of the su	bstances w all lower	vithin the manufactu level materials for w	rer listed i hich the n	tem. Note: i nanufacture	if the item is an as r has engineering	sembly with low responsibility.	
			Form Type Distribute	*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information														
Company name* Compan			nique ID			Unique ID Authority				Respons	Response Date*			
nsemi										2025-05	-13			
Contact Name Title - Contact				]	Phone - Contact*				Email - Contact*					
Product-Env-Stewards Produc			ct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
Authorized Representative* Titl			Representative			Phone - Representative*			Email - Representative*					
roduct-Env-Stewards	Product Envir	duct Enviro Compliance NA				Product-Env-Stewards@onsemi.com								
Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type		
	AR0135 A0-DRE	35AT2M25XUE 1MP 1/3 CIS SO RBR				2025-05-13		М	MY5		198.94	mg	Each	
Ianufacturing Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy J-ST			J-STD-020 MSL	Rating	Peak Proce	ss Body Te	mperature	Max Time at Peak	Temperat	ure Numl	ber of Reflow Cyc	les		
SnAgCu CU Alloy 3				3		260		С	30	secon	ds 3			
omments														
TTENTION: MSL 3 Rated item requires	Bake and E	Dry Pack (after	electrical test)											
or more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	46.746	mg		Misc.	proprietary data		0.1776	mg
			Supplier	Silicon (Si)	7440-21-3		46.1056	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4628	mg
Die Attach	2.852	mg	Supplier	Siloxanes and Silicones, di-Me, hydroxy- terminated, reaction products with Me hydrogen siloxanes and trimethoxy(3- (oxiranylmethoxy)propyl)silane	153890-18-7		0.5704	mg
			Supplier	1,1'-(Methylenedi-p- phenylene)bismaleimide	13676-54-5		1.2834	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.2852	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.2852	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.2852	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.1426	mg
Imaging Lens	29.239	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.5388	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.5388	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		0.1541	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.5388	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.5388	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.5388	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		21.3907	mg
Lid Attach	1.459	mg	Supplier	2,2-Bis(glycidyloxyphenyl)propane polymer	25085-99-8		0.3647	mg
			Supplier	3,4-EPOXYCYCLOHEXYLMETHYL	2386-87-0		1.0578	mg
			Supplier	Misc.	Proprietary Data		0.0365	mg
Mold Compound	43.49	mg	Supplier	Triphenylphosphine	603-35-0		0.2175	mg
			Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.2175	mg
			Supplier	Oxirane	39817-09-9		8.698	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		8.698	mg
			Supplier	Misc.	Proprietary Data		2.1745	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		21.3101	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		2.1745	mg
Solder Ball	35.868	mg	Supplier	Silver (Ag)	7440-22-4		1.076	mg

			Supplier	Tin (Sn)	7440-31-5	34.6126	mg
			Supplier	Copper (Cu)	7440-50-8	0.1793	mg
Solder Mask	4.22	mg		Epoxy resin	proprietary data	0.5064	mg
			Supplier	Acrylate	Proprietary Data	1.612	mg
			Supplier	Talc	14807-96-6	0.1139	mg
			Supplier	Miscellaneous	Trade Secret	0.1561	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	1.8315	mg
Substrate Copper Foil	3.09	mg	Supplier	Copper (Cu)	7440-50-8	3.09	mg
Substrate - Core Material	16.24	mg		Epoxy resin	proprietary data	3.5192	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	12.7208	mg
Substrate Plating-Au	0.29	mg	Supplier	Gold (Au)	7440-57-5	0.29	mg
Substrate Plating-Cu	14.49	mg	Supplier	Copper (Cu)	7440-50-8	14.49	mg
Substrate Plating-Ni	0.67	mg	В	Nickel (Ni)	7440-02-0	0.67	mg
Wire Bond - Au	0.286	mg	Supplier	Gold (Au)	7440-57-5	0.286	mg